

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	13	("5521435" "5672548" "5909057" "5959353" "6020637" "6051888" "6104093" "6122171" "6313521" "6349032" "6441499" "6469381" "6507104").PN.	US-PGPUB; USPAT	OR	OFF	2005/10/12 13:46
L2	20	("20010015492" "20020006718" "20020185734" "20030034569" "5172213" "5311080" "5339216" "5493153" "5610442" "5639694" "5650663" "5679978" "5705851" "5986885" "6236568" "6251706" "6323066" "6414385" "6462405" "6525421").PN.	US-PGPUB; USPAT	OR	OFF	2005/10/12 11:33
L4	6	"20030226253".pn. "20030189245".pn. "20020180035".pn. "20030160309".pn. "20030075812".pn. "5609889".pn.	US-PGPUB; USPAT	OR	OFF	2005/10/12 10:34
L5	9	"5977626".pn. "5736785".pn. "5877552".pn. "6631078".pn. "6037658".pn. "20020005578".pn. "6656770".pn. "5773362".pn. "5444025".pn.	US-PGPUB; USPAT	OR	OFF	2005/10/12 11:10
L6	2	de-10015962-\$.did.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/10/12 10:21
L7	4	"6800948".pn. "6933176".pn. "6737755".pn. "6818472".pn.	US-PGPUB; USPAT	OR	OFF	2005/10/12 12:38
L8	1	"4698662".pn.	US-PGPUB; USPAT	OR	OFF	2005/10/12 12:39
L9	4	jp-02278783-\$.did. jp-09232690-\$.did.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/10/12 12:39
L10	1533	438/113.ccls. 438/122.ccls.	US-PGPUB; USPAT	OR	OFF	2005/10/12 14:33
L11	858	((mold\$6 encapsula\$8 ((epoxy plastic) near2 packag\$6)) and (heat near2 (sink spread\$6 dissipat\$6))).clm.	US-PGPUB	OR	ON	2005/10/12 14:39
L12	592	((die dice chip integrated semiconductor ic) and (mold\$6 encapsula\$8 ((epoxy plastic) near2 packag\$6)) and (heat near2 (sink spread\$6 dissipat\$6))).clm.	US-PGPUB	OR	ON	2005/10/12 14:41

L13	338	((die dice chip integrated semiconductor ic) and (mold\$6 encapsula\$8 ((epoxy plastic) near2 packag\$6)) and (heat near2 (sink spread\$6 dissipat\$6)) and ((wire near bond\$6) bga (solder adj (ball bump\$6)) (substrate near4 (wir\$6 packag\$6 trace))))).clm.	US-PGPUB	OR	ON	2005/10/12 14:45
L14	93	((die dice chip integrated semiconductor ic) and (mold\$6 encapsula\$8 ((epoxy plastic) near2 packag\$6)) and (heat near2 (sink spread\$6 dissipat\$6)) and ((wire near bond\$6) bga (solder adj (ball bump\$6)) (substrate near4 (wir\$6 packag\$6 trace))) and (singulat\$6 dic\$6 section\$6 saw\$6 cut\$6)).clm.	US-PGPUB	OR	ON	2005/10/12 14:46